

SN65LVDS22, SN65LVDM22 DUAL MULTIPLEXED LVDS REPEATERS

SLLS315C–DECEMBER 1998 – REVISED JUNE 2002

- Meets or Exceeds the Requirements of ANSI TIA/EIA-644-1995 Standard
- Designed for Clock Rates up to 200 MHz (400 Mbps)
- Designed for Data Rates up to 250 Mbps
- Pin Compatible With SN65LVDS122 and SN65LVDT122, 1.5 Gbps 2x2 Crosspoint Switch From TI
- ESD Protection Exceeds 12 kV on Bus Pins
- Operates From a Single 3.3-V Supply
- Low-Voltage Differential Signaling With Output Voltages of 350 mV Into:
 - 100-Ω Load (SN65LVDS22)
 - 50-Ω Load (SN65LVDM22)
- Propagation Delay Time; 4 ns Typ
- Power Dissipation at 400 Mbps of 150 mW
- Bus Pins Are High Impedance When Disabled or With V_{CC} Less Than 1.5 V
- LVTTTL Levels Are 5 V Tolerant
- Open-Circuit Fail Safe Receiver

description

The SN65LVDS22 and SN65LVDM22 are differential line drivers and receivers that use low-voltage differential signaling (LVDS) to achieve signaling rates as high as 400 Mbps. The receiver outputs can be switched to either or both drivers through the multiplexer control signals S0 and S1. This allows the flexibility to perform splitter or signal routing functions with a single device.

The TIA/EIA-644 standard compliant electrical interface provides a minimum differential output voltage magnitude of 247 mV into a 100-Ω load and receipt of 100 mV signals with up to 1 V of ground potential difference between a transmitter and receiver. The SN65LVDM22 doubles the output drive current to achieve LVDS levels with a 50-Ω load.

The intended application of these devices and signaling technique is for both point-to-point baseband (single termination) and multipoint (double termination) data transmissions over controlled impedance media. The transmission media may be printed-circuit board traces, backplanes, or cables. (Note: The ultimate rate and distance of data transfer is dependent upon the attenuation characteristics of the media, the noise coupling to the environment, and other application specific characteristics).

The SN65LVDS22 and SN65LVDM22 are characterized for operation from -40°C to 85°C .



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

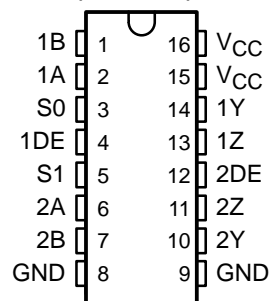
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

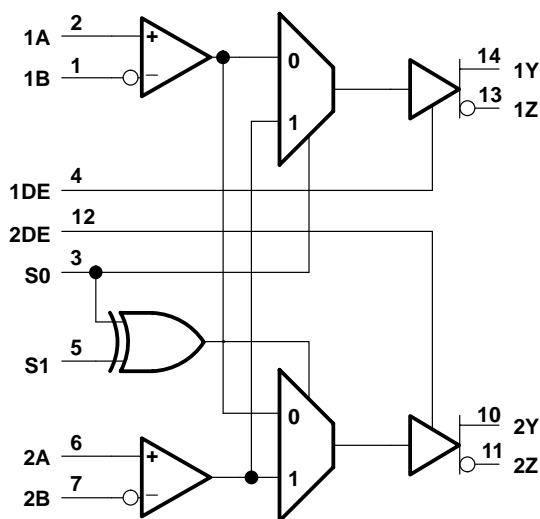
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SN65LVDS22D and SN65LVDS22PW (Marked as LVDS22)
SN65LVDM22D and SN65LVDM22PW (Marked as LVDM22)
(TOP VIEW)



logic diagram (positive logic)



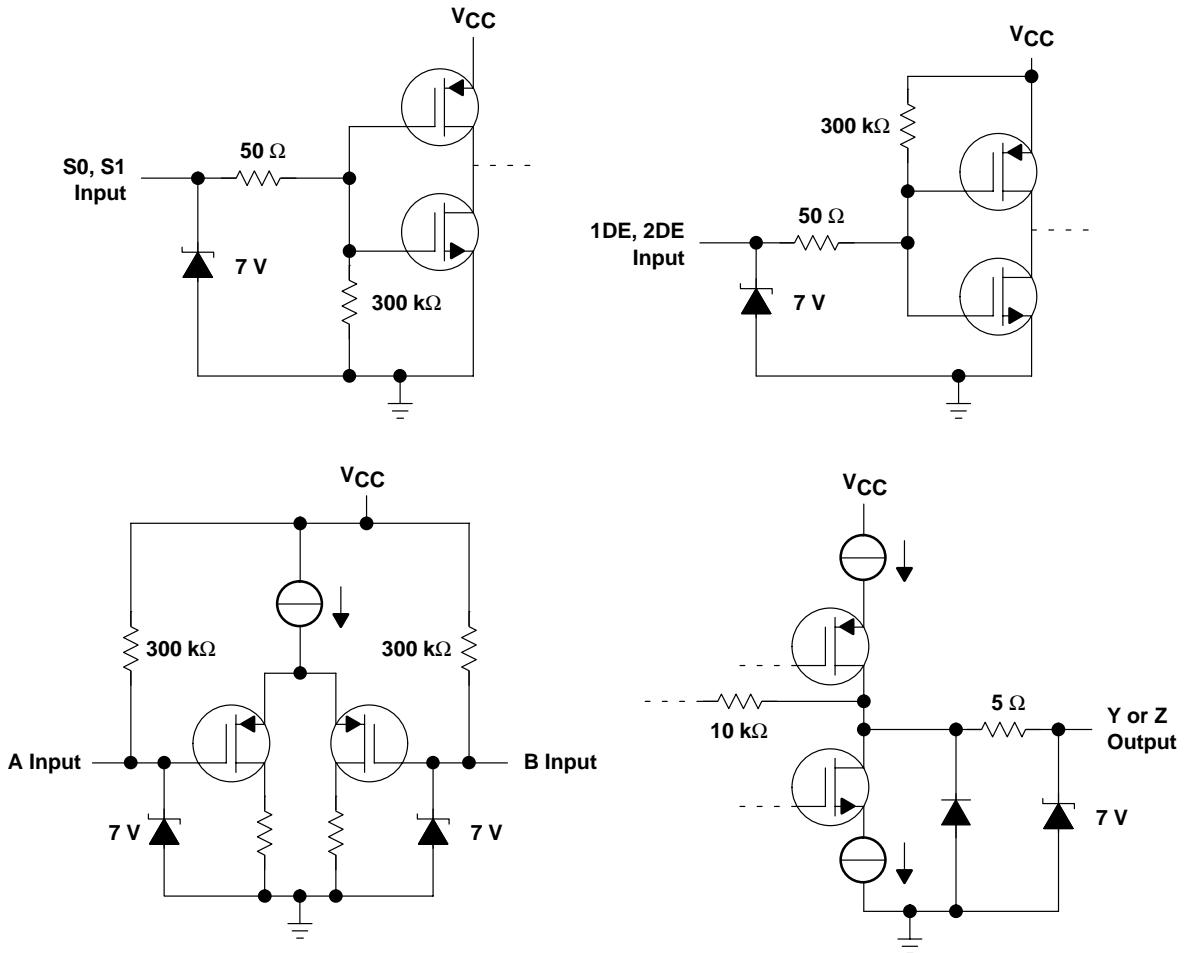
MUX TRUTH TABLE

INPUT		OUTPUT		FUNCTION
S1	S0	1Y/1Z	2Y/2Z	
0	0	1A/1B	1A/1B	Splitter
0	1	2A/2B	2A/2B	Splitter
1	0	1A/1B	2A/2B	Router
1	1	2A/2B	1A/1B	Router

SN65LVDS22, SN65LVDM22 DUAL MULTIPLEXED LVDS REPEATERS

SLLS315C—DECEMBER 1998—REVISED JUNE 2002

equivalent input and output schematic diagrams



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SLLS315C–DECEMBER 1998 – REVISED JUNE 2002

absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage range, V_{CC} (see Note 1)	–0.5 V to 4 V
Voltage range: (DE, S0, S1)	–0.5 V to 6 V
(Y, Z, A, and B)	–0.5 V to 4 V
Electrostatic discharge: A, B, Y, Z and GND (see Note 2)	Class 3, A:12 kV, B:600 V
All pins	Class 3, A:5 kV, B:500 V
Continuous power dissipation	See Dissipation Rating Table
Storage temperature range	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential I/O bus voltages, are with respect to network ground terminal.
2. Tested in accordance with MIL-STD-883C Method 3015.7.

DISSIPATION RATING TABLE

PACKAGE	$T_A \leq 25^\circ\text{C}$ POWER RATING	DERATING FACTOR‡ ABOVE $T_A = 25^\circ\text{C}$	$T_A = 85^\circ\text{C}$ POWER RATING
D	1110 mW	8.9 mW/°C	577 mW
PW	839 mW	6.7 mW/°C	437 mW

‡ This is the inverse of the junction-to-ambient thermal resistance when board-mounted and with no air flow.

recommended operating conditions

	MIN	NOM	MAX	UNIT	
Supply voltage, V_{CC}	3	3.3	3.6	V	
High-level input voltage, V_{IH}	S0, S1, 1DE, 2DE			2	V
Low-level input voltage, V_{IL}	S0, S1, 1DE, 2DE			0.8	V
Magnitude of differential input voltage, $ V_{ID} $	0.1		0.6	V	
Common-mode input voltage, V_{IC} (see Figure 1)	$\frac{ V_{ID} }{2}$	$2.4 - \frac{ V_{ID} }{2}$		V	
		$V_{CC} - 0.8$		V	
Operating free-air temperature, T_A	–40		85	°C	

timing requirements

PARAMETER		MIN	NOM	MAX	UNIT
t_{su}	Input to select setup time		1.6		ns
t_h	Input to select hold time		–1		ns
t_{switch}	Select to switch output		3.2	5	ns

See Figure 6



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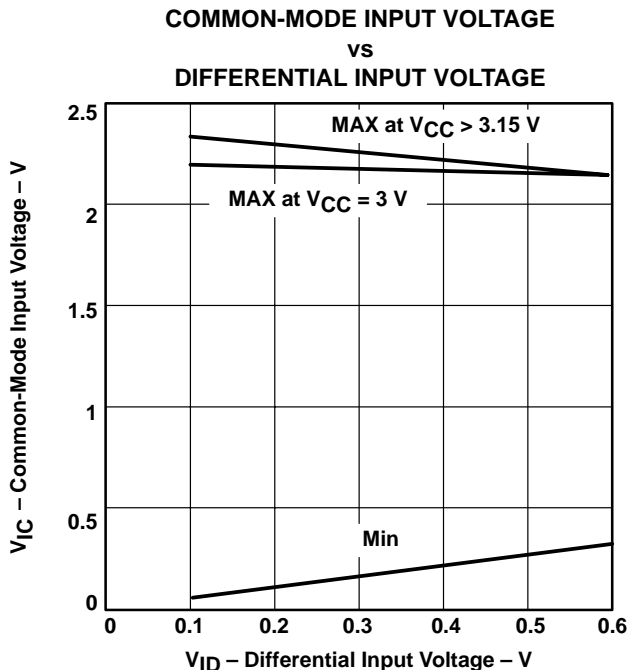


Figure 1. Common-Mode Input Voltage vs Differential Input Voltage

receiver electrical characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
V _{IT+}	Positive-going differential input voltage threshold			100	mV
V _{IT-}	Negative-going differential input voltage threshold	-100			mV
I _I	Input current (A or B inputs)				μA
	V _I = 0 V	-2		-20	
	V _I = 2.4 V	-1.2			
I _{I(OFF)}	Power-off input current (A or B inputs)			20	μA
	V _{CC} = 0 V				



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SN65LVDS22, SN65LVDM22 DUAL MULTIPLEXED LVDS REPEATERS

SLLS315C– DECEMBER 1998 – REVISED JUNE 2002

receiver/driver electrical characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT	
V_{OD}	Differential output voltage magnitude	$R_L = 100 \Omega$ ('LVDS22), $R_L = 50 \Omega$ ('LVDM22)	See Figure 2	247	340	454	mV	
ΔV_{OD}	Change in differential output voltage magnitude between logic states			-50		50	mV	
$V_{OC(SS)}$	Steady-state common-mode output voltage		See Figure 3	1.125		1.375	V	
$\Delta V_{OC(SS)}$	Change in steady-state common-mode output voltage between logic states			-50	3	50	mV	
$V_{OC(PP)}$	Peak-to-peak common-mode output voltage					150	mV	
I_{CC}	Supply current	No Load		8	12	mA		
		$R_L = 100 \Omega$ ('LVDS22)		13	20			
		$R_L = 50 \Omega$ ('LVDM22)		21	27			
		Disabled		3	6			
I_{IH}	High-level input current	DE S0, S1	$V_{IH} = 5 V$			-10	μA	
						20		
I_{IL}	Low-level input current	DE S0, S1	$V_{IL} = 0.8 V$			-10	μA	
						10		
I_{OS}	Short-circuit output current		V_{OY} or $V_{OZ} = 0 V$, ('LVDS22) $V_{OD} = 0 V$,			-10	mA	
			V_{OY} or $V_{OZ} = 0 V$, ('LVDM22) $V_{OD} = 0 V$,			-10		
I_{OZ}	High-impedance output current		$V_{OD} = 600 mV$		0.015	± 1		μA
			$V_O = 0 V$ or V_{CC}			0.015		
$I_{O(OFF)}$	Power-off output current		$V_{CC} = 0 V$, $V_O = 3.6 V$		0.015	± 1	μA	
C_{IN}	Input capacitance				3		pF	

† All typical values are at 25°C and with a 3.3-V supply.

SN65LVDS22, SN65LVDM22 DUAL MULTIPLEXED LVDS REPEATERS

SLLS315C– DECEMBER 1998 – REVISED JUNE 2002

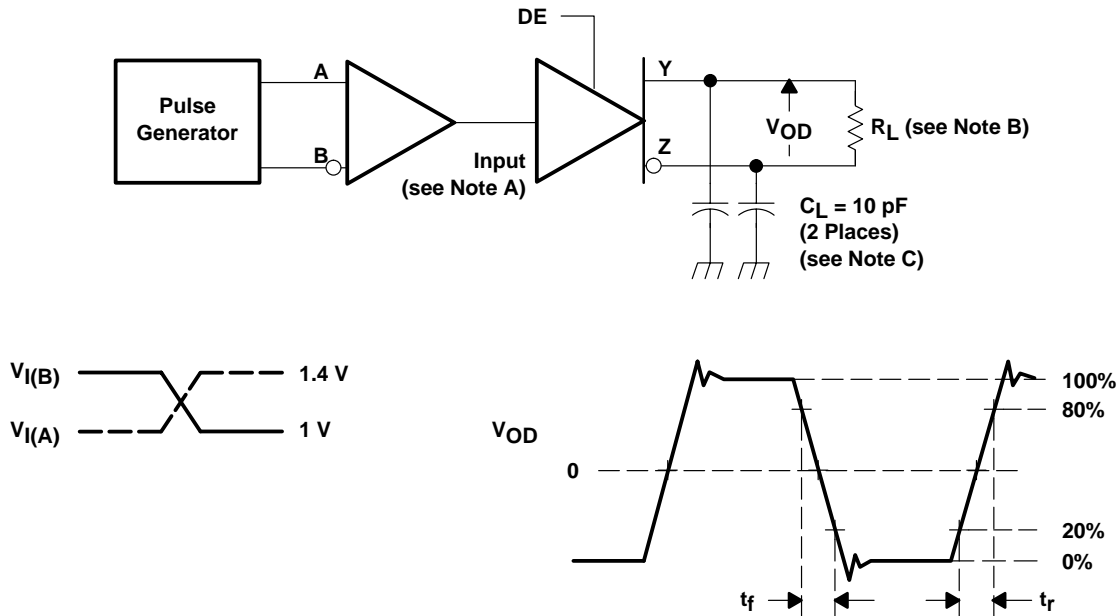
differential receiver to driver switching characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT	
t _{PLH}	Differential propagation delay time, low-to-high	C _L = 10 pF, See Figure 4		4	6	ns	
t _{PHL}	Differential propagation delay time, high-to-low			4	6	ns	
t _{sk(p)}	Pulse skew (t _{PHL} – t _{PLH})			0.2		ns	
t _r	Transition time, low-to-high		SN65LVDS22		1	1.5	ns
t _r	Transition time, low-to-high		SN65LVDM22		0.8	1.3	ns
t _f	Transition time, high-to-low		SN65LVDS22		1	1.5	ns
t _f	Transition time, high-to-low		SN65LVDM22		0.8	1.3	ns
t _{PHZ}	Propagation delay time, high-level-to-high-impedance output	See Figure 5		4	10	ns	
t _{PLZ}	Propagation delay time, low-level-to-high-impedance output			5	10	ns	
t _{PZH}	Propagation delay time, high-impedance-to-high-level output			5	10	ns	
t _{PZL}	Propagation delay time, high-impedance-to-low-level output			6	10	ns	
t _{PHL-R1-Dx}	Channel-to-channel skew, receiver to driver‡			0.2		ns	
t _{PLH-R1-Dx}				0.2			
t _{PHL-R2-Dx}				0.2			
t _{PLH-R2-Dx}				0.2			
f _{max}	Maximum operating frequency	All channels switching		200		MHz	

† All typical values are at 25°C and with a 3.3-V supply.

‡ These parametric values are measured over supply voltage and temperature ranges recommended for the device.

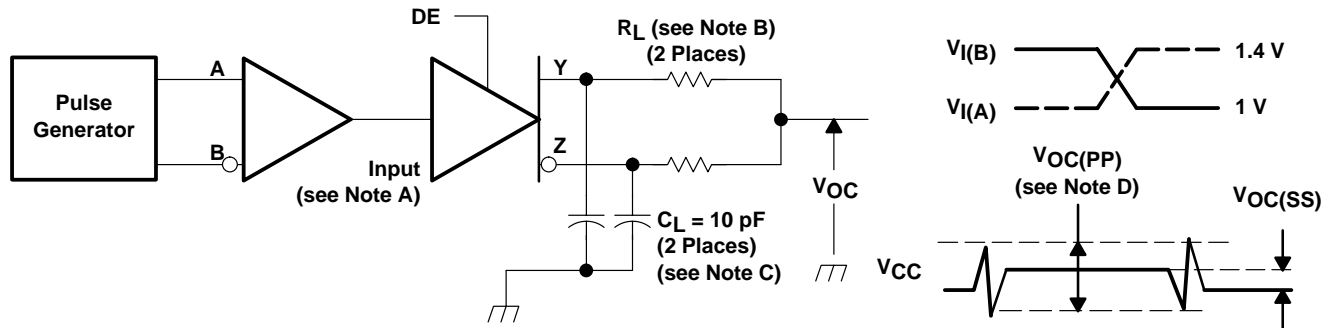
PARAMETER MEASUREMENT INFORMATION



- NOTES: A. All input pulses are supplied by a generator having the following characteristics: t_r or $t_f \leq 1$ ns, pulse repetition rate (PRR) = 50 Mpps, pulse width = 10 ± 0.2 ns.
 B. $R_L = 100 \Omega$ or $50 \Omega \pm 1\%$
 C. C_L includes instrumentation and fixture capacitance within 6 mm of the D.U.T.

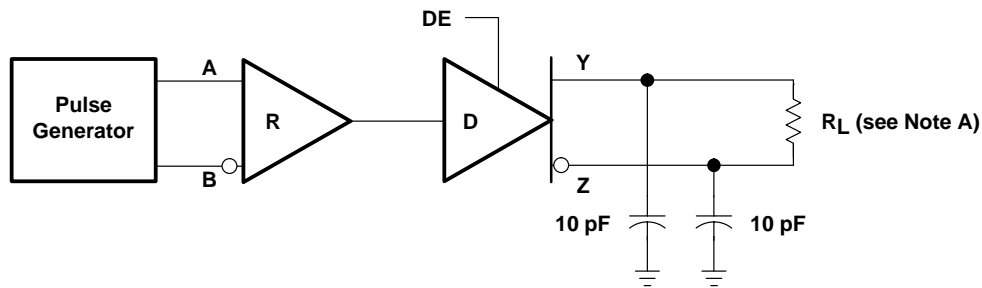
Figure 2. Test Circuit and Voltage Definitions for the Differential Output Signal

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. All input pulses are supplied by a generator having the following characteristics: t_r or $t_f \leq 1$ ns, pulse repetition rate (PRR) = 50 Mpps, pulse width = 10 ± 0.2 ns.
 B. $R_L = 100 \Omega$ or $50 \Omega \pm 1\%$
 C. C_L includes instrumentation and fixture capacitance within 6 mm of the D.U.T.
 D. The measurement of $V_{OC(PP)}$ is made on test equipment with a -3 dB bandwidth of at least 300 MHz.

Figure 3. Test Circuit and Definitions for the Driver Common-Mode Output Voltage



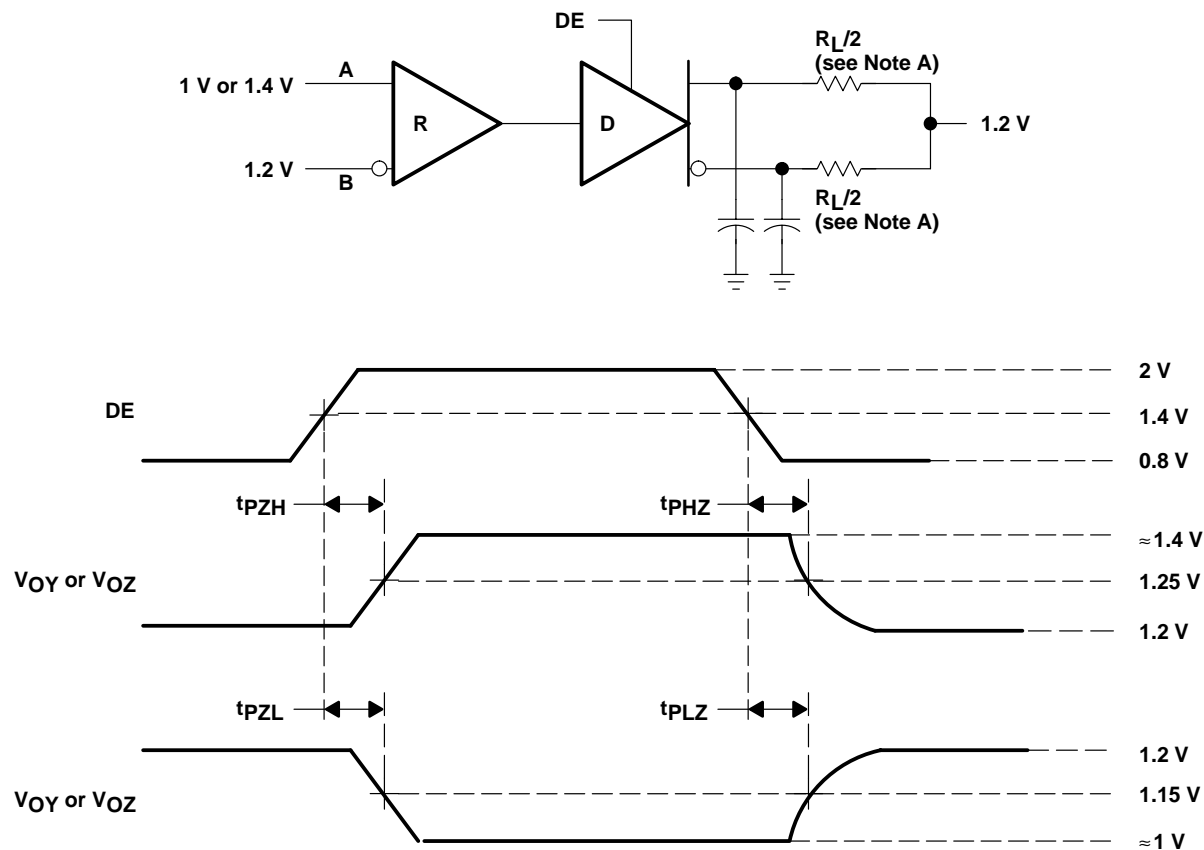
- NOTES: A. $R_L = 100 \Omega$ or $50 \Omega \pm 1\%$
 B. All input pulses are supplied by a generator having the following characteristics: pulse repetition rate (PRR) = 50 Mpps, pulse width = 10 ± 0.2 ns.

Figure 4. Differential Receiver to Driver Propagation Delay and Driver Transition Time Waveforms

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SLLS315C- DECEMBER 1998 - REVISED JUNE 2002

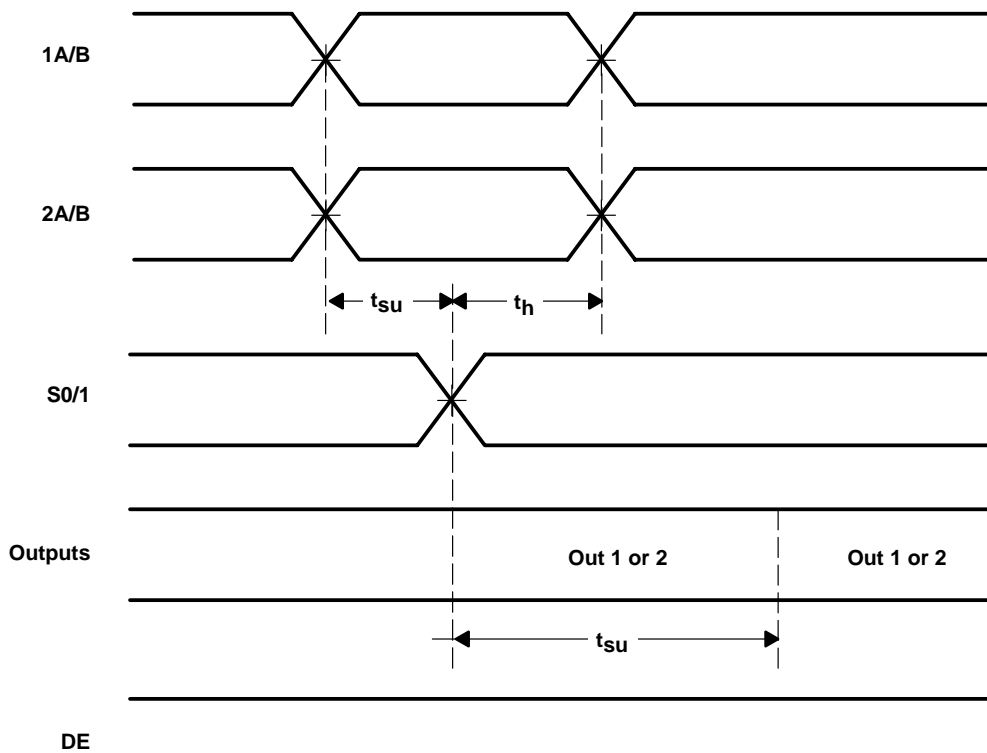
PARAMETER MEASUREMENT INFORMATION



- NOTES: A. $R_L = 100 \Omega$ or $50 \Omega \pm 1\%$
 B. All input pulses are supplied by a generator having the following characteristics: pulse repetition rate (PRR) = 0.5 Mpps, pulse width = 500 ± 10 ns.

Figure 5. Enable and Disable Timing Circuit

PARAMETER MEASUREMENT INFORMATION



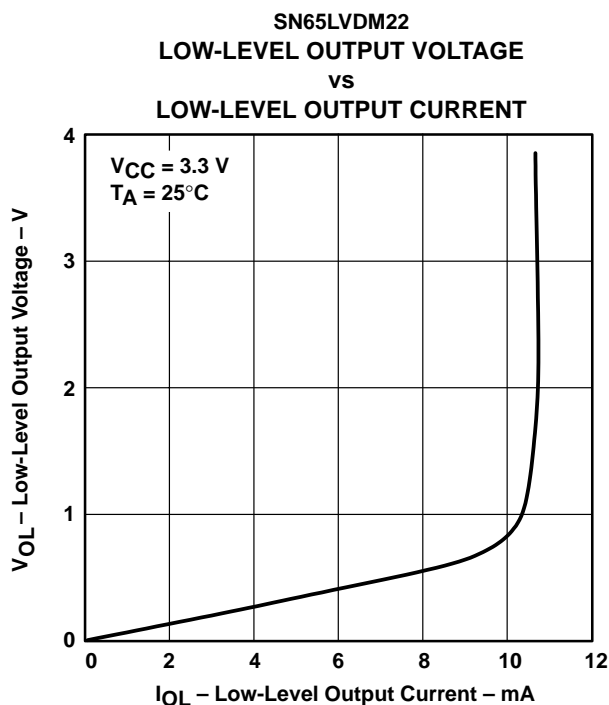
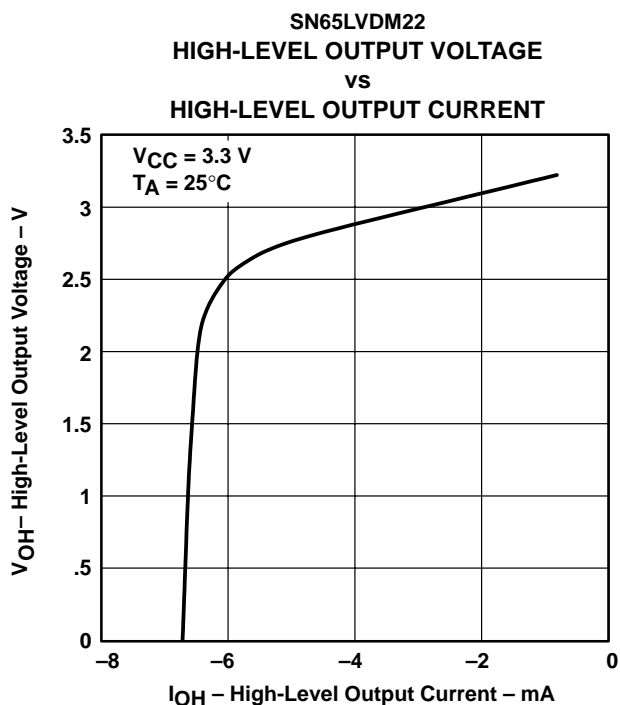
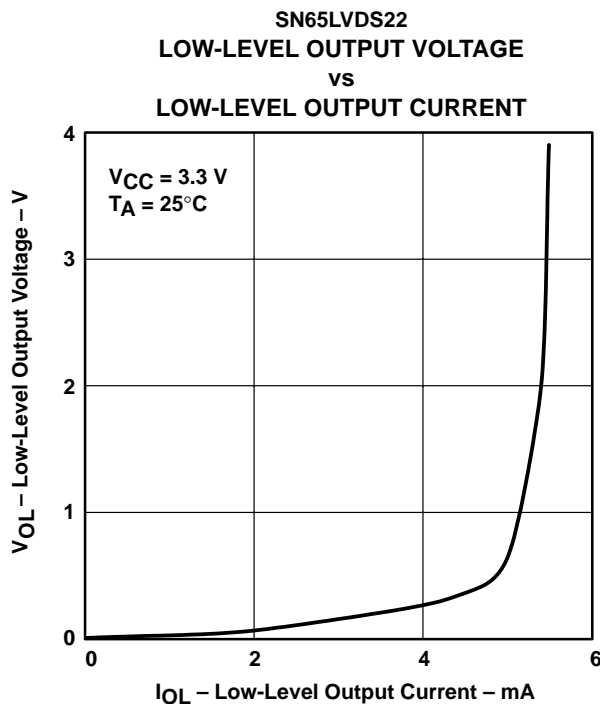
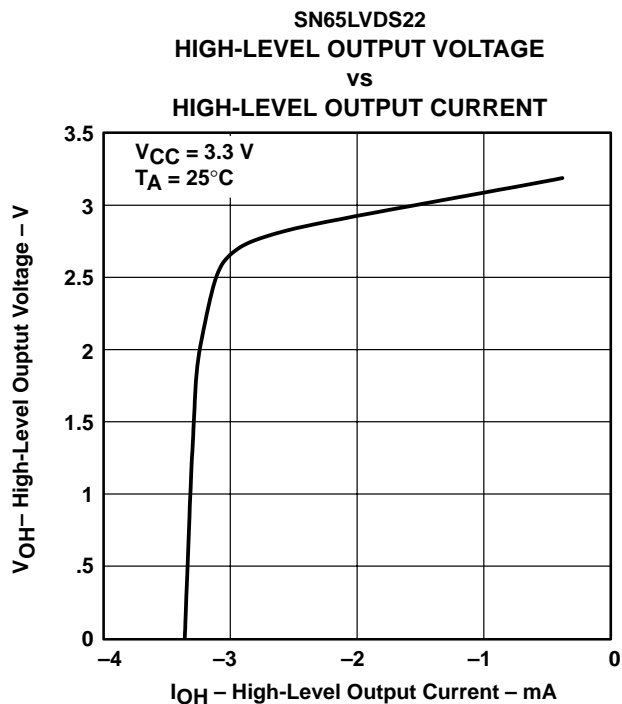
NOTE: t_{su} and t_h times specify that data must be in a stable state before and after MUX control switches.

Figure 6. Input-to-Select for Both Rising and Falling Edge Setup and Hold Times

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SLLS315C– DECEMBER 1998 – REVISED JUNE 2002

TYPICAL CHARACTERISTICS



APPLICATION INFORMATION

fail safe

One of the most common problems with differential signaling applications is how the system responds when no differential voltage is present on the signal pair. The LVDS receiver is like most differential line receivers, in that its output logic state can be indeterminate when the differential input voltage is between -100 mV and 100 mV and within its recommended input common-mode voltage range. However, TI's LVDS receiver is different in how it handles the open-input circuit situation.

Open-circuit means that there is little or no input current to the receiver from the data line itself. This could be when the driver is in a high-impedance state or the cable is disconnected. When this occurs, the LVDS receiver pulls each line of the signal pair to near V_{CC} through $300\text{-k}\Omega$ resistors as shown in Figure 11. The fail-safe feature uses an AND gate with input voltage thresholds at about 2.3 V to detect this condition and force the output to a high-level regardless of the differential input voltage.

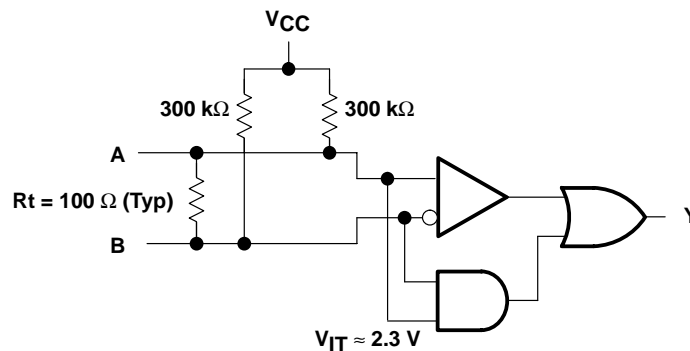


Figure 11. Open-Circuit Fail Safe of the LVDS Receiver

It is only under these conditions that the output of the receiver is valid with less than a 100 mV differential input voltage magnitude. The presence of the termination resistor, R_t , does not affect the fail-safe function as long as it is connected as shown in Figure 11. Other termination circuits may allow a dc current to ground that could defeat the pullup currents from the receiver and the fail-safe feature.

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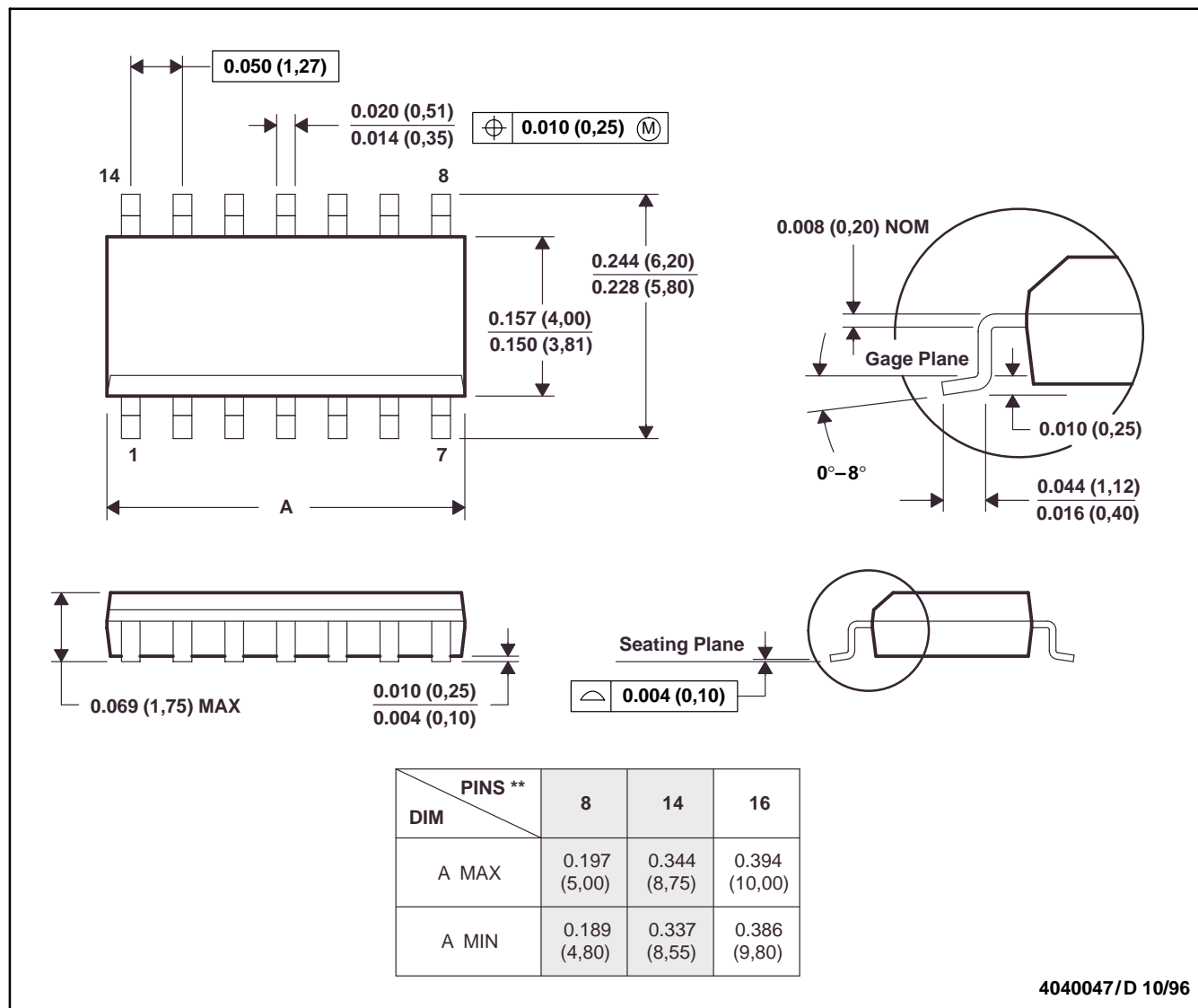
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MECHANICAL DATA

D (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PIN SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).
 D. Falls within JEDEC MS-012

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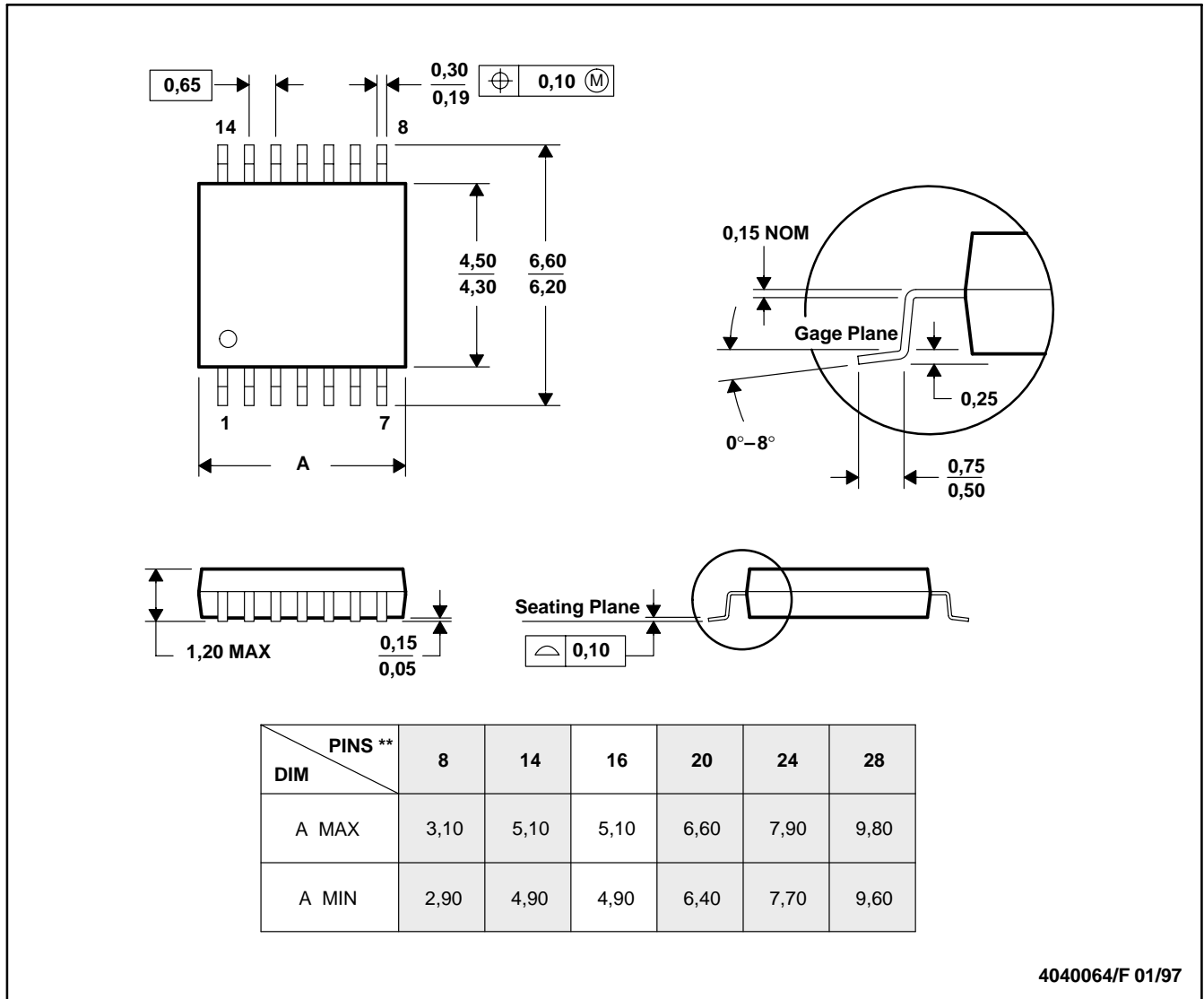
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MECHANICAL DATA

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 - Falls within JEDEC MO-153

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN65LVDM22D	ACTIVE	SOIC	D	16	40	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1YEAR/ Level-1-220C-UNLIM
SN65LVDM22DR	ACTIVE	SOIC	D	16	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1YEAR/ Level-1-220C-UNLIM
SN65LVDM22PW	ACTIVE	TSSOP	PW	16	90	None	CU NIPDAU	Level-1-220C-UNLIM
SN65LVDM22PWR	ACTIVE	TSSOP	PW	16	2000	None	CU NIPDAU	Level-1-220C-UNLIM
SN65LVDS22D	ACTIVE	SOIC	D	16	40	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1YEAR/ Level-1-220C-UNLIM
SN65LVDS22DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LVDS22DR	ACTIVE	SOIC	D	16	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1YEAR/ Level-1-220C-UNLIM
SN65LVDS22PW	ACTIVE	TSSOP	PW	16	90	None	CU NIPDAU	Level-1-220C-UNLIM
SN65LVDS22PWR	ACTIVE	TSSOP	PW	16	2000	None	CU NIPDAU	Level-1-220C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - May not be currently available - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

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Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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